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- (54) Title of the Invention:
  
- (57) Abstract

The invention relates to a center pad type BGA package. An object of the invention is to provide a center pad type BGA package characterized in that a metal pattern is formed on the active surface of a chip such that wire bonding is achieved between the metal pattern and chip pads and between the metal pattern and substrate pads, thereby preventing formation of bonding wires of a long loop. This object is accomplished by providing a center pad type BGA package including a chip formed with chip pads and a metal pattern at an active surface thereof, a substrate bonded to the chip via an adhesive coated on an inactive surface of the chip, the substrate being formed with substrate pads at an upper surface thereof and with solder pads at a lower surface thereof, first bonding wires for electrically connecting the chip pads with the metal pattern, second bonding wires for electrically connecting the substrate pads with the metal pattern, solder balls formed on the substrate via respective solder pads; and an encapsulate for encapsulating the chip and the bonding wires. In accordance with the center pad type BGA package, which includes the chip provided with the metal pattern, there is no sweeping of the bonding wires. Also, the process for manufacturing the package can be simplified.